



P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$ $I_{D}\left(\Omega\right)$			
- 20	0.039 at V _{GS} = - 4.5 V	- 4.7		
	0.052 at V _{GS} = - 2.5 V	- 4.1		
	0.068 at V _{GS} = - 1.8 V	- 3.5		

FEATURES

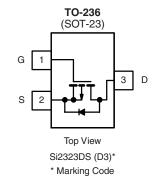
- Halogen-free According to IEC 61249-2-21 **Available**
- TrenchFET® Power MOSFET

COMPLIANT

HALOGEN FREE

APPLICATIONS

- Load Switch
- PA Switch



Ordering Information: Si2323DS-T1

Si2323DS-T1-E3 (Lead (Pb)-free)

Si2323DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS	$\Gamma_A = 25 ^{\circ}\text{C}$, unle	ss otherwise i	noted		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	- 20		V
Gate-Source Voltage		V _{GS}	± 8		V
Continuous Dunin Comment /T 450 °C) 8 h	T _A = 25 °C	- I _D	- 4.7	- 3.7	^
Continuous Drain Current (T _J = 150 °C) ^{a, b}	T _A = 70 °C		- 3.8	- 2.9	
Pulsed Drain Current		I _{DM}	- 20		Α
Continuous Source Current (Diode Conduction) ^{a, b}		I _S	- 1.0	- 0.6	
Maximum Power Dissipation ^{a, b}	T _A = 25 °C	- P _D	1.25	0.75	W
	T _A = 70 °C		0.8	0.48	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum landing to Audienta	t ≤ 5 s	R _{thJA}	75	100	°C/W
Maximum Junction-to-Ambient ^a	Steady State		120	166	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	40	50	

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

Si2323DS

Vishay Siliconix



SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
Parameter	Symbol		Limits				
		Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 20			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = -250 \mu A$	- 0.40		- 1.0	ľ	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 8 V$			± 100	nA	
Zero Gate Voltage Drain Current	lana	V _{DS} = - 16 V, V _{GS} = 0 V			- 1	μΑ	
	I _{DSS}	V_{DS} = - 16 V, V_{GS} = 0 V, T_J = 55 °C			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -4.7 \text{ A}$		0.031	0.039		
Drain-Source On-Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 4.1 A		0.041	0.052	Ω	
		V _{GS} = - 1.8 V, I _D = - 2.0 A		0.054	0.068		
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -5 \text{ V}, I_D = -4.7 \text{ A}$		16		S	
Diode Forward Voltage	V_{SD}	I _S = - 1.0 A, V _{GS} = 0 V		- 0.7	- 1.2	V	
Dynamic ^b							
Total Gate Charge	Qg	V 40VV 45V		12.5	19	nC	
Gate-Source Charge	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}$ $I_{D} \cong -4.7 \text{ A}$		1.7			
Gate-Drain Charge	Q_{gd}	D= 4.7 A		3.3			
Input Capacitance	C _{iss}			1020			
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		191		pF	
Reverse Transfer Capacitance	C _{rss}			140		1	
Switching ^c			•	•			
Turn-On Time	t _{d(on)}	V 40V B 40 5		25	40		
	t _r	$V_{DD} = -10 \text{ V}, R_L = 10 \Omega$		43	65]	
Turn Off Time	$I_D \cong -1.0 \text{ A, V}_{GEN} = -4.5 \text{ V}$ The second seco			71	110	ns	
Turn-Off Time	t _f	· ·G = 5 22		48	75		

Notes:

- a. Pulse test: PW \leq 300 μ s, duty cycle \leq 2 %.
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.

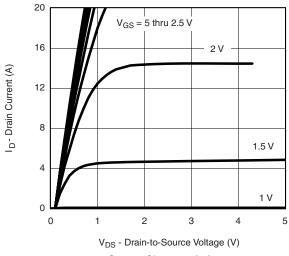
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



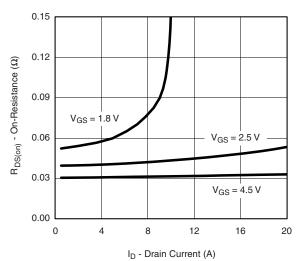




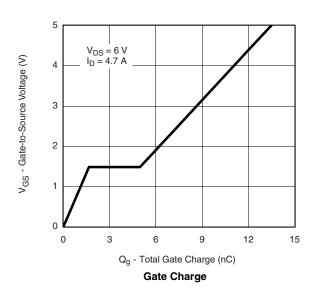
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Output Characteristics

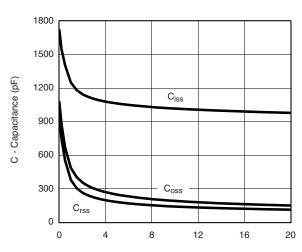


On-Resistance vs. Drain Current

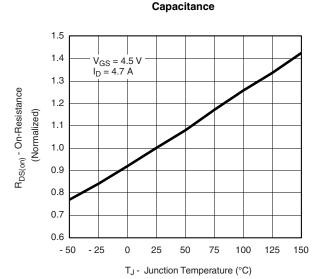


V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



 V_{DS} - Drain-to-Source Voltage (V)

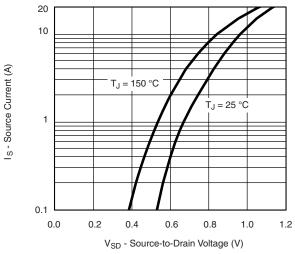


On-Resistance vs. Junction Temperature

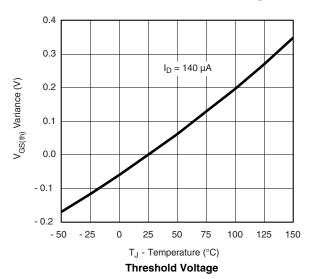
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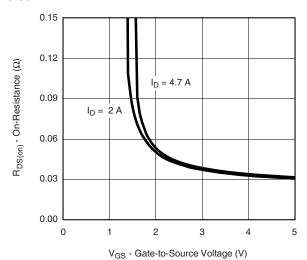
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

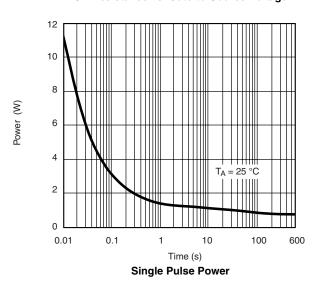


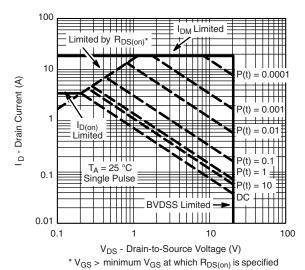
Source-Drain Diode Forward Voltage





On-Resistance vs. Gate-to-Source Voltage

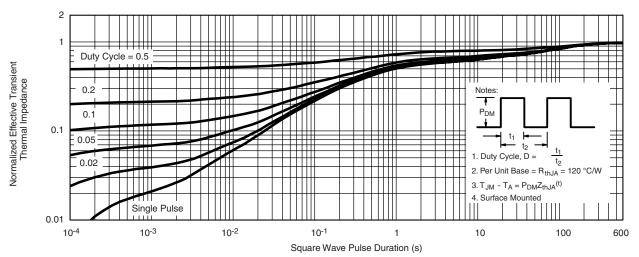




Safe Operating Area



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?72024.



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